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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	1536
Number of Logic Elements/Cells	6912
Total RAM Bits	131072
Number of I/O	312
Number of Gates	411955
Voltage - Supply	1.71V ~ 1.89V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	456-BBGA
Supplier Device Package	456-FBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xcv300e-7fg456i

For in-circuit debugging, an optional download and read-back cable is available. This cable connects the FPGA in the target system to a PC or workstation. After downloading the design into the FPGA, the designer can single-step the

logic, readback the contents of the flip-flops, and so observe the internal logic state. Simple modifications can be downloaded into the system in a matter of minutes.

Configuration

Virtex-E devices are configured by loading configuration data into the internal configuration memory. Note that attempting to load an incorrect bitstream causes configuration to fail and can damage the device.

Some of the pins used for configuration are dedicated pins, while others can be re-used as general purpose inputs and outputs once configuration is complete.

The following are dedicated pins:

- Mode pins (M2, M1, M0)
- Configuration clock pin (CCLK)
- PROGRAM pin
- DONE pin
- Boundary Scan pins (TDI, TDO, TMS, TCK)

Depending on the configuration mode chosen, CCLK can be an output generated by the FPGA, or can be generated externally and provided to the FPGA as an input. The PROGRAM pin must be pulled High prior to reconfiguration.

Note that some configuration pins can act as outputs. For correct operation, these pins require a V_{CCO} of 3.3 V or 2.5 V. At 3.3 V the pins operate as LVTTTL, and at 2.5 V they

operate as LVCMOS. All affected pins fall in banks 2 or 3. The configuration pins needed for SelectMap (CS, Write) are located in bank 1.

Configuration Modes

Virtex-E supports the following four configuration modes.

- Slave-serial mode
- Master-serial mode
- SelectMAP mode
- Boundary Scan mode (JTAG)

The Configuration mode pins (M2, M1, M0) select among these configuration modes with the option in each case of having the IOB pins either pulled up or left floating prior to configuration. The selection codes are listed in [Table 8](#).

Configuration through the Boundary Scan port is always available, independent of the mode selection. Selecting the Boundary Scan mode simply turns off the other modes. The three mode pins have internal pull-up resistors, and default to a logic High if left unconnected. However, it is recommended to drive the configuration mode pins externally.

Table 8: Configuration Codes

Configuration Mode	M2 ⁽¹⁾	M1	M0	CCLK Direction	Data Width	Serial D _{out}	Configuration Pull-ups ⁽¹⁾
Master-serial mode	0	0	0	Out	1	Yes	No
Boundary Scan mode	1	0	1	N/A	1	No	No
SelectMAP mode	1	1	0	In	8	No	No
Slave-serial mode	1	1	1	In	1	Yes	No
Master-serial mode	1	0	0	Out	1	Yes	Yes
Boundary Scan mode	0	0	1	N/A	1	No	Yes
SelectMAP mode	0	1	0	In	8	No	Yes
Slave-serial mode	0	1	1	In	1	Yes	Yes

Notes:

1. M2 is sampled continuously from power up until the end of the configuration. Toggling M2 while INIT is being held externally Low can cause the configuration pull-up settings to change.

Configuration through the TAP uses the CFG_IN instruction. This instruction allows data input on TDI to be converted into data packets for the internal configuration bus.

The following steps are required to configure the FPGA through the Boundary Scan port (when using TCK as a start-up clock).

1. Load the CFG_IN instruction into the Boundary Scan instruction register (IR).
2. Enter the Shift-DR (SDR) state.
3. Shift a configuration bitstream into TDI.
4. Return to Run-Test-Idle (RTI).
5. Load the JSTART instruction into IR.
6. Enter the SDR state.
7. Clock TCK through the startup sequence.
8. Return to RTI.

Configuration and readback via the TAP is always available. The Boundary Scan mode is selected by a <101> or <001> on the mode pins (M2, M1, M0). For details on TAP characteristics, refer to XAPP139.

Configuration Sequence

The configuration of Virtex-E devices is a three-phase process. First, the configuration memory is cleared. Next, configuration data is loaded into the memory, and finally, the logic is activated by a start-up process.

Configuration is automatically initiated on power-up unless it is delayed by the user, as described below. The configuration process can also be initiated by asserting $\overline{\text{PROGRAM}}$. The end of the memory-clearing phase is signalled by $\overline{\text{INIT}}$ going High, and the completion of the entire process is signalled by DONE going High.

The power-up timing of configuration signals is shown in Figure 20.

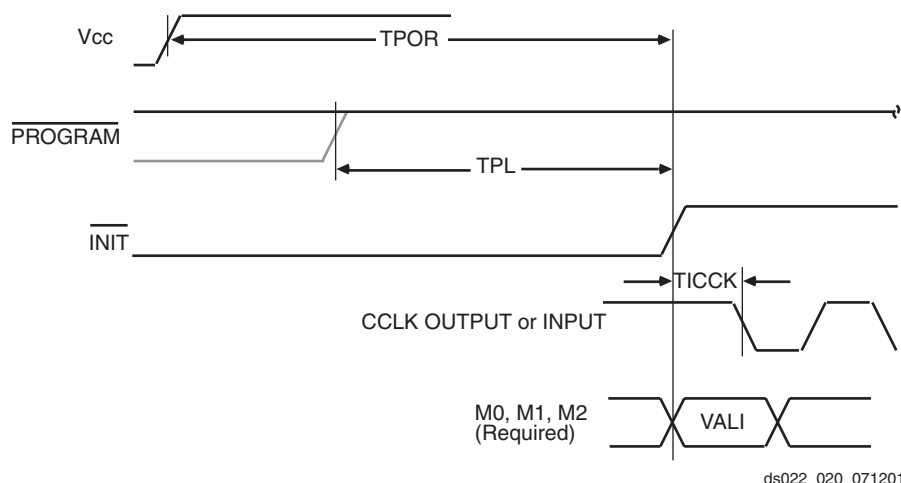


Figure 20: Power-Up Timing Configuration Signals

The corresponding timing characteristics are listed in Table 12.

Table 12: Power-up Timing Characteristics

Description	Symbol	Value	Units
Power-on Reset ¹	T_{POR}	2.0	ms, max
Program Latency	T_{PL}	100.0	μs , max
CCLK (output) Delay	T_{ICCK}	0.5	μs , min
		4.0	μs , max
Program Pulse Width	T_{PROGRAM}	300	ns, min

Notes:

1. T_{POR} delay is the initialization time required after V_{CCINT} and V_{CCO} in Bank 2 reach the recommended operating voltage.

Delaying Configuration

$\overline{\text{INIT}}$ can be held Low using an open-drain driver. An open-drain is required since $\overline{\text{INIT}}$ is a bidirectional open-drain pin that is held Low by the FPGA while the configuration memory is being cleared. Extending the time that the pin is Low causes the configuration sequencer to wait. Thus, configuration is delayed by preventing entry into the phase where data is loaded.

Start-Up Sequence

The default Start-up sequence is that one CCLK cycle after DONE goes High, the global 3-state signal (GTS) is released. This permits device outputs to turn on as necessary.

One CCLK cycle later, the Global Set/Reset (GSR) and Global Write Enable (GWE) signals are released. This permits

Verilog Initialization Example

```

module MYMEM (CLK, WE, ADDR, DIN, DOUT);
input CLK, WE;
input [8:0] ADDR;
input [7:0] DIN;
output [7:0] DOUT;

wire logic0, logic1;

//synopsys dc_script_begin
//set_attribute ram0 INIT_00
"0123456789ABCDEF0123456789ABCDEF0123456789ABCDEF0123456789ABCDEF" -type string
//set_attribute ram0 INIT_01
"FEDCBA9876543210FEDCBA9876543210FEDCBA9876543210FEDCBA9876543210" -type string
//synopsys dc_script_end

assign logic0 = 1'b0;
assign logic1 = 1'b1;

RAMB4_S8 ram0 (.WE(WE), .EN(logic1), .RST(logic0), .CLK(CLK), .ADDR(ADDR), .DI(DIN),
.DO(DOUT));
//synopsys translate_off
defparam ram0.INIT_00 =
256h'0123456789ABCDEF0123456789ABCDEF0123456789ABCDEF0123456789ABCDEF;
defparam ram0.INIT_01 =
256h'FEDCBA9876543210FEDCBA9876543210FEDCBA9876543210FEDCBA9876543210;
//synopsys translate_on
endmodule

```

Using SelectI/O

The Virtex-E FPGA series includes a highly configurable, high-performance I/O resource, called SelectI/O™ to provide support for a wide variety of I/O standards. The SelectI/O resource is a robust set of features including programmable control of output drive strength, slew rate, and input delay and hold time. Taking advantage of the flexibility and SelectI/O features and the design considerations described in this document can improve and simplify system level design.

Introduction

As FPGAs continue to grow in size and capacity, the larger and more complex systems designed for them demand an increased variety of I/O standards. Furthermore, as system clock speeds continue to increase, the need for high performance I/O becomes more important.

While chip-to-chip delays have an increasingly substantial impact on overall system speed, the task of achieving the desired system performance becomes more difficult with the proliferation of low-voltage I/O standards. SelectI/O, the revolutionary input/output resources of Virtex-E devices, resolve this potential problem by providing a highly configurable, high-performance alternative to the I/O resources of more conventional programmable devices. Virtex-E SelectI/O features combine the flexibility and time-to-market advantages of programmable logic with the high performance previously available only with ASICs and custom ICs.

Each SelectI/O block can support up to 20 I/O standards. Supporting such a variety of I/O standards allows the support of a wide variety of applications, from general purpose standard applications to high-speed low-voltage memory buses.

SelectI/O blocks also provide selectable output drive strengths and programmable slew rates for the LVTTTL output buffers, as well as an optional, programmable weak pull-up, weak pull-down, or weak “keeper” circuit ideal for use in external bussing applications.

Each Input/Output Block (IOB) includes three registers, one each for the input, output, and 3-state signals within the IOB. These registers are optionally configurable as either a D-type flip-flop or as a level sensitive latch.

The input buffer has an optional delay element used to guarantee a zero hold time requirement for input signals registered within the IOB.

The Virtex-E SelectI/O features also provide dedicated resources for input reference voltage (V_{REF}) and output source voltage (V_{CCO}), along with a convenient banking system that simplifies board design.

By taking advantage of the built-in features and wide variety of I/O standards supported by the SelectI/O features, system-level design and board design can be greatly simplified and improved.

Fundamentals

Modern bus applications, pioneered by the largest and most influential companies in the digital electronics industry, are commonly introduced with a new I/O standard tailored specifically to the needs of that application. The bus I/O standards provide specifications to other vendors who create products designed to interface with these applications. Each standard often has its own specifications for current, voltage, I/O buffering, and termination techniques.

The ability to provide the flexibility and time-to-market advantages of programmable logic is increasingly dependent on the capability of the programmable logic device to support an ever increasing variety of I/O standards.

The SelectI/O resources feature highly configurable input and output buffers which provide support for a wide variety of I/O standards. As shown in [Table 18](#), each buffer type can support a variety of voltage requirements.

Table 18: Virtex-E Supported I/O Standards

I/O Standard	Output V_{CCO}	Input V_{CCO}	Input V_{REF}	Board Termination Voltage (V_{TT})
LVTTL	3.3	3.3	N/A	N/A
LVC MOS2	2.5	2.5	N/A	N/A
LVC MOS18	1.8	1.8	N/A	N/A
SSTL3 I & II	3.3	N/A	1.50	1.50
SSTL2 I & II	2.5	N/A	1.25	1.25
GTL	N/A	N/A	0.80	1.20
GTL+	N/A	N/A	1.0	1.50
HSTL I	1.5	N/A	0.75	0.75
HSTL III & IV	1.5	N/A	0.90	1.50
CTT	3.3	N/A	1.50	1.50
AGP-2X	3.3	N/A	1.32	N/A
PCI33_3	3.3	3.3	N/A	N/A
PCI66_3	3.3	3.3	N/A	N/A
BLVDS & LVDS	2.5	N/A	N/A	N/A
LVPECL	3.3	N/A	N/A	N/A

Overview of Supported I/O Standards

This section provides a brief overview of the I/O standards supported by all Virtex-E devices.

While most I/O standards specify a range of allowed voltages, this document records typical voltage values only. Detailed information on each specification can be found on the Electronic Industry Alliance Jedec website at:

<http://www.jedec.org>

LVTTL — Low-Voltage TTL

The Low-Voltage TTL, or LVTTL standard is a general purpose EIA/JESDSA standard for 3.3V applications that uses an LVTTL input buffer and a Push-Pull output buffer. This standard requires a 3.3V output source voltage (V_{CCO}), but does not require the use of a reference voltage (V_{REF}) or a termination voltage (V_{TT}).

LVC MOS2 — Low-Voltage CMOS for 2.5 Volts

The Low-Voltage CMOS for 2.5 Volts or lower, or LVC MOS2 standard is an extension of the LVC MOS standard (JESD 8-5) used for general purpose 2.5V applications. This standard requires a 2.5V output source voltage (V_{CCO}), but does not require the use of a reference voltage (V_{REF}) or a board termination voltage (V_{TT}).

LVC MOS18 — 1.8 V Low Voltage CMOS

This standard is an extension of the LVC MOS standard. It is used in general purpose 1.8 V applications. The use of a reference voltage (V_{REF}) or a board termination voltage (V_{TT}) is not required.

PCI — Peripheral Component Interface

The Peripheral Component Interface, or PCI standard specifies support for both 33 MHz and 66 MHz PCI bus applications. It uses a LVTTL input buffer and a Push-Pull output buffer. This standard does not require the use of a reference voltage (V_{REF}) or a board termination voltage (V_{TT}), however, it does require a 3.3V output source voltage (V_{CCO}).

GTL — Gunning Transceiver Logic Terminated

The Gunning Transceiver Logic, or GTL standard is a high-speed bus standard (JESD8.3) invented by Xerox. Xilinx has implemented the terminated variation for this standard. This standard requires a differential amplifier input buffer and an Open Drain output buffer.

GTL+ — Gunning Transceiver Logic Plus

The Gunning Transceiver Logic Plus, or GTL+ standard is a high-speed bus standard (JESD8.3) first used by the Pentium Pro processor.

HSTL — High-Speed Transceiver Logic

The High-Speed Transceiver Logic, or HSTL standard is a general purpose high-speed, 1.5V bus standard sponsored by IBM (EIA/JESD 8-6). This standard has four variations or classes. SelectI/O devices support Class I, III, and IV. This

SSTL3_I

A sample circuit illustrating a valid termination technique for SSTL3_I appears in Figure 49. DC voltage specifications appear in Table 28.

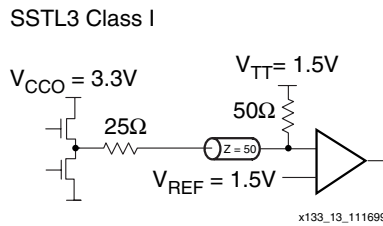


Figure 49: Terminated SSTL3 Class I

Table 28: SSTL3_I Voltage Specifications

Parameter	Min	Typ	Max
V_{CCO}	3.0	3.3	3.6
$V_{REF} = 0.45 \times V_{CCO}$	1.3	1.5	1.7
$V_{TT} = V_{REF}$	1.3	1.5	1.7
$V_{IH} = V_{REF} + 0.2$	1.5	1.7	3.9 ⁽¹⁾
$V_{IL} = V_{REF} - 0.2$	-0.3 ⁽²⁾	1.3	1.5
$V_{OH} = V_{REF} + 0.6$	1.9	-	-
$V_{OL} = V_{REF} - 0.6$	-	-	1.1
I_{OH} at V_{OH} (mA)	-8	-	-
I_{OL} at V_{OL} (mA)	8	-	-

Notes:

- V_{IH} maximum is $V_{CCO} + 0.3$
- V_{IL} minimum does not conform to the formula

SSTL3_II

A sample circuit illustrating a valid termination technique for SSTL3_II appears in Figure 50. DC voltage specifications appear in Table 29.

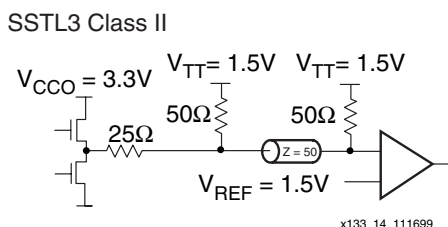


Figure 50: Terminated SSTL3 Class II

Table 29: SSTL3_II Voltage Specifications

Parameter	Min	Typ	Max
V_{CCO}	3.0	3.3	3.6
$V_{REF} = 0.45 \times V_{CCO}$	1.3	1.5	1.7
$V_{TT} = V_{REF}$	1.3	1.5	1.7
$V_{IH} = V_{REF} + 0.2$	1.5	1.7	3.9 ⁽¹⁾
$V_{IL} = V_{REF} - 0.2$	-0.3 ⁽²⁾	1.3	1.5
$V_{OH} = V_{REF} + 0.8$	2.1	-	-
$V_{OL} = V_{REF} - 0.8$	-	-	0.9
I_{OH} at V_{OH} (mA)	-16	-	-
I_{OL} at V_{OL} (mA)	16	-	-

Notes:

- V_{IH} maximum is $V_{CCO} + 0.3$
- V_{IL} minimum does not conform to the formula

SSTL2_I

A sample circuit illustrating a valid termination technique for SSTL2_I appears in Figure 51. DC voltage specifications appear in Table 30.

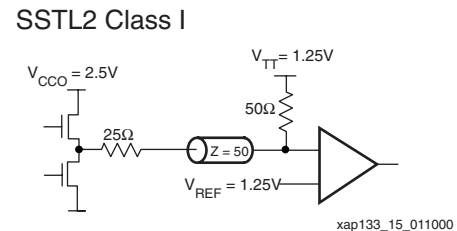


Figure 51: Terminated SSTL2 Class I

Table 30: SSTL2_I Voltage Specifications

Parameter	Min	Typ	Max
V_{CCO}	2.3	2.5	2.7
$V_{REF} = 0.5 \times V_{CCO}$	1.15	1.25	1.35
$V_{TT} = V_{REF} + N^{(1)}$	1.11	1.25	1.39
$V_{IH} = V_{REF} + 0.18$	1.33	1.43	3.0 ⁽²⁾
$V_{IL} = V_{REF} - 0.18$	-0.3 ⁽³⁾	1.07	1.17
$V_{OH} = V_{REF} + 0.61$	1.76	-	-
$V_{OL} = V_{REF} - 0.61$	-	-	0.74
I_{OH} at V_{OH} (mA)	-7.6	-	-
I_{OL} at V_{OL} (mA)	7.6	-	-

Notes:

- N must be greater than or equal to -0.04 and less than or equal to 0.04.
- V_{IH} maximum is $V_{CCO} + 0.3$.
- V_{IL} minimum does not conform to the formula.

LVTTL

LVTTL requires no termination. DC voltage specifications appears in [Table 34](#).

Table 34: LVTTL Voltage Specifications

Parameter	Min	Typ	Max
V _{CCO}	3.0	3.3	3.6
V _{REF}	-	-	-
V _{TT}	-	-	-
V _{IH}	2.0	-	3.6
V _{IL}	-0.5	-	0.8
V _{OH}	2.4	-	-
V _{OL}	-	-	0.4
I _{OH} at V _{OH} (mA)	-24	-	-
I _{OL} at V _{OL} (mA)	24	-	-

Notes:

- Note: V_{OL} and V_{OH} for lower drive currents sample tested.

LVC MOS2

LVC MOS2 requires no termination. DC voltage specifications appear in [Table 35](#).

Table 35: LVC MOS2 Voltage Specifications

Parameter	Min	Typ	Max
V _{CCO}	2.3	2.5	2.7
V _{REF}	-	-	-
V _{TT}	-	-	-
V _{IH}	1.7	-	3.6
V _{IL}	-0.5	-	0.7
V _{OH}	1.9	-	-
V _{OL}	-	-	0.4
I _{OH} at V _{OH} (mA)	-12	-	-
I _{OL} at V _{OL} (mA)	12	-	-

LVC MOS18

LVC MOS18 does not require termination. [Table 36](#) lists DC voltage specifications.

Table 36: LVC MOS18 Voltage Specifications

Parameter	Min	Typ	Max
V _{CCO}	1.70	1.80	1.90
V _{REF}	-	-	-
V _{TT}	-	-	-
V _{IH}	0.65 × V _{CCO}	-	1.95
V _{IL}	-0.5	-	0.2 × V _{CCO}
V _{OH}	V _{CCO} - 0.4	-	-
V _{OL}	-	-	0.4
I _{OH} at V _{OH} (mA)	-8	-	-
I _{OL} at V _{OL} (mA)	8	-	-

AGP-2X

The specification for the AGP-2X standard does not document a recommended termination technique. DC voltage specifications appear in [Table 37](#).

Table 37: AGP-2X Voltage Specifications

Parameter	Min	Typ	Max
V _{CCO}	3.0	3.3	3.6
V _{REF} = N × V _{CCO} ⁽¹⁾	1.17	1.32	1.48
V _{TT}	-	-	-
V _{IH} = V _{REF} + 0.2	1.37	1.52	-
V _{IL} = V _{REF} - 0.2	-	1.12	1.28
V _{OH} = 0.9 × V _{CCO}	2.7	3.0	-
V _{OL} = 0.1 × V _{CCO}	-	0.33	0.36
I _{OH} at V _{OH} (mA)	Note 2	-	-
I _{OL} at V _{OL} (mA)	Note 2	-	-

Notes:

- N must be greater than or equal to 0.39 and less than or equal to 0.41.
- Tested according to the relevant specification.

Input/Output Standard	V_{IL}		V_{IH}		V_{OL}	V_{OH}	I_{OL}	I_{OH}
	V, Min	V, Max	V, Min	V, Max	V, Max	V, Min	mA	mA
CTT	-0.5	$V_{REF} - 0.2$	$V_{REF} + 0.2$	3.6	$V_{REF} - 0.4$	$V_{REF} + 0.4$	8	-8
AGP	-0.5	$V_{REF} - 0.2$	$V_{REF} + 0.2$	3.6	10% V_{CCO}	90% V_{CCO}	Note 2	Note 2

Notes:

1. V_{OL} and V_{OH} for lower drive currents are sample tested.
2. Tested according to the relevant specifications.
3. DC input and output levels for HSTL18 (HSTL I/O standard with V_{CCO} of 1.8 V) are provided in an HSTL white paper on www.xilinx.com.

LVDS DC Specifications

DC Parameter	Symbol	Conditions	Min	Typ	Max	Units
Supply Voltage	V_{CCO}		2.375	2.5	2.625	V
Output High Voltage for Q and $\bar{Q}$	V_{OH}	$R_T = 100 \Omega$ across Q and $\bar{Q}$ signals	1.25	1.425	1.6	V
Output Low Voltage for Q and $\bar{Q}$	V_{OL}	$R_T = 100 \Omega$ across Q and $\bar{Q}$ signals	0.9	1.075	1.25	V
Differential Output Voltage (Q - $\bar{Q}$), Q = High ($\bar{Q}$ - Q), $\bar{Q}$ = High	V_{ODIFF}	$R_T = 100 \Omega$ across Q and $\bar{Q}$ signals	250	350	450	mV
Output Common-Mode Voltage	V_{OCM}	$R_T = 100 \Omega$ across Q and $\bar{Q}$ signals	1.125	1.25	1.375	V
Differential Input Voltage (Q - $\bar{Q}$), Q = High ($\bar{Q}$ - Q), $\bar{Q}$ = High	V_{IDIFF}	Common-mode input voltage = 1.25 V	100	350	NA	mV
Input Common-Mode Voltage	V_{ICM}	Differential input voltage = ± 350 mV	0.2	1.25	2.2	V

Note: Refer to the Design Consideration section for termination schematics.

LVPECL DC Specifications

These values are valid at the output of the source termination pack shown under **LVPECL**, with a 100Ω differential load only. The V_{OH} levels are 200 mV below standard LVPECL levels and are compatible with devices tolerant of lower common-mode ranges. The following table summarizes the DC output specifications of LVPECL.

DC Parameter	Min	Max	Min	Max	Min	Max	Units
V_{CCO}	3.0		3.3		3.6		V
V_{OH}	1.8	2.11	1.92	2.28	2.13	2.41	V
V_{OL}	0.96	1.27	1.06	1.43	1.30	1.57	V
V_{IH}	1.49	2.72	1.49	2.72	1.49	2.72	V
V_{IL}	0.86	2.125	0.86	2.125	0.86	2.125	V
Differential Input Voltage	0.3	-	0.3	-	0.3	-	V

IOB Output Switching Characteristics Standard Adjustments

Output delays terminating at a pad are specified for LVTTL with 12 mA drive and fast slew rate. For other standards, adjust the delays by the values shown.

			Speed Grade				Units
Description	Symbol	Standard	Min	-8	-7	-6	
Output Delay Adjustments							
Standard-specific adjustments for output delays terminating at pads (based on standard capacitive load, Csl)	T _{OLVTTL_S2}	LVTTL, Slow, 2 mA	4.2	+14.7	+14.7	+14.7	ns
	T _{OLVTTL_S4}	4 mA	2.5	+7.5	+7.5	+7.5	ns
	T _{OLVTTL_S6}	6 mA	1.8	+4.8	+4.8	+4.8	ns
	T _{OLVTTL_S8}	8 mA	1.2	+3.0	+3.0	+3.0	ns
	T _{OLVTTL_S12}	12 mA	1.0	+1.9	+1.9	+1.9	ns
	T _{OLVTTL_S16}	16 mA	0.9	+1.7	+1.7	+1.7	ns
	T _{OLVTTL_S24}	24 mA	0.8	+1.3	+1.3	+1.3	ns
	T _{OLVTTL_F2}	LVTTL, Fast, 2 mA	1.9	+13.1	+13.1	+13.1	ns
	T _{OLVTTL_F4}	4 mA	0.7	+5.3	+5.3	+5.3	ns
	T _{OLVTTL_F6}	6 mA	0.20	+3.1	+3.1	+3.1	ns
	T _{OLVTTL_F8}	8 mA	0.10	+1.0	+1.0	+1.0	ns
	T _{OLVTTL_F12}	12 mA	0.0	0.0	0.0	0.0	ns
	T _{OLVTTL_F16}	16 mA	−0.10	−0.05	−0.05	−0.05	ns
	T _{OLVTTL_F24}	24 mA	−0.10	−0.20	−0.20	−0.20	ns
	T _{OLVCMOS_2}	LVC MOS2	0.10	+0.09	+0.09	+0.09	ns
	T _{OLVCMOS_18}	LVC MOS18	0.10	+0.7	+0.7	+0.7	ns
	T _{OLVDS}	LVDS	−0.39	−1.2	−1.2	−1.2	ns
	T _{OLVPECL}	LVPECL	−0.20	−0.41	−0.41	−0.41	ns
	T _{OPCI33_3}	PCI, 33 MHz, 3.3 V	0.50	+2.3	+2.3	+2.3	ns
	T _{OPCI66_3}	PCI, 66 MHz, 3.3 V	0.10	−0.41	−0.41	−0.41	ns
	T _{OGTL}	GTL	0.6	+0.49	+0.49	+0.49	ns
	T _{OGTLP}	GTL+	0.7	+0.8	+0.8	+0.8	ns
	T _{OHSTL_I}	HSTL I	0.10	−0.51	−0.51	−0.51	ns
	T _{OHSTL_III}	HSTL III	−0.10	−0.91	−0.91	−0.91	ns
	T _{OHSTL_IV}	HSTL IV	−0.20	−1.01	−1.01	−1.01	ns
	T _{OSSTL2_I}	SSTL2 I	−0.10	−0.51	−0.51	−0.51	ns
	T _{OSSTL2_II}	SSTL2 II	−0.20	−0.91	−0.91	−0.91	ns
	T _{OSSTL3_I}	SSTL3 I	−0.20	−0.51	−0.51	−0.51	ns
	T _{OSSTL3_II}	SSTL3 II	−0.30	−1.01	−1.01	−1.01	ns
	T _{OCTT}	CTT	0.0	−0.61	−0.61	−0.61	ns
	T _{OAGP}	AGP	−0.1	−0.91	−0.91	−0.91	ns

CLB Switching Characteristics

Delays originating at F/G inputs vary slightly according to the input used, see [Figure 2](#). The values listed below are worst-case. Precise values are provided by the timing analyzer.

		Speed Grade ⁽¹⁾				Units
Description	Symbol	Min	-8	-7	-6	
Combinatorial Delays						
4-input function: F/G inputs to X/Y outputs	T _{ILO}	0.19	0.40	0.42	0.47	ns, max
5-input function: F/G inputs to F5 output	T _{IF5}	0.36	0.76	0.8	0.9	ns, max
5-input function: F/G inputs to X output	T _{IF5X}	0.35	0.74	0.8	0.9	ns, max
6-input function: F/G inputs to Y output via F6 MUX	T _{IF6Y}	0.35	0.74	0.9	1.0	ns, max
6-input function: F5IN input to Y output	T _{F5INY}	0.04	0.11	0.20	0.22	ns, max
Incremental delay routing through transparent latch to XQ/YQ outputs	T _{IFNCTL}	0.27	0.63	0.7	0.8	ns, max
BY input to YB output	T _{BYYB}	0.19	0.38	0.46	0.51	ns, max
Sequential Delays						
FF Clock CLK to XQ/YQ outputs	T _{CKO}	0.34	0.78	0.9	1.0	ns, max
Latch Clock CLK to XQ/YQ outputs	T _{CKLO}	0.40	0.77	0.9	1.0	ns, max
Setup and Hold Times before/after Clock CLK						
4-input function: F/G Inputs	T _{ICK} / T _{CKI}	0.39 / 0	0.9 / 0	1.0 / 0	1.1 / 0	ns, min
5-input function: F/G inputs	T _{IF5CK} / T _{CKIF5}	0.55 / 0	1.3 / 0	1.4 / 0	1.5 / 0	ns, min
6-input function: F5IN input	T _{F5INCK} / T _{CKF5IN}	0.27 / 0	0.6 / 0	0.8 / 0	0.8 / 0	ns, min
6-input function: F/G inputs via F6 MUX	T _{IF6CK} / T _{CKIF6}	0.58 / 0	1.3 / 0	1.5 / 0	1.6 / 0	ns, min
BX/BY inputs	T _{DICK} / T _{CKDI}	0.25 / 0	0.6 / 0	0.7 / 0	0.8 / 0	ns, min
CE input	T _{CECK} / T _{CKCE}	0.28 / 0	0.55 / 0	0.7 / 0	0.7 / 0	ns, min
SR/BY inputs (synchronous)	T _{RCK} / T _{CKR}	0.24 / 0	0.46 / 0	0.52 / 0	0.6 / 0	ns, min
Clock CLK						
Minimum Pulse Width, High	T _{CH}	0.56	1.2	1.3	1.4	ns, min
Minimum Pulse Width, Low	T _{CL}	0.56	1.2	1.3	1.4	ns, min
Set/Reset						
Minimum Pulse Width, SR/BY inputs	T _{RPW}	0.94	1.9	2.1	2.4	ns, min
Delay from SR/BY inputs to XQ/YQ outputs (asynchronous)	T _{RQ}	0.39	0.8	0.9	1.0	ns, max
Toggle Frequency (MHz) (for export control)	F _{TOG}	-	416	400	357	MHz

Notes:

1. A Zero "0" Hold Time listing indicates no hold time or a negative hold time. Negative values can not be guaranteed "best-case", but if a "0" is listed, there is no positive hold time.

Table 13: BG432 Differential Pin Pair Summary
XCV300E, XCV400E, XC600E

Pair	Bank	P Pin	N Pin	AO	Other Functions
48	2	N1	P4	√	D3
49	2	P3	P2	4	-
50	2	R3	R4	1	VREF
51	2	R1	T3	√	-
52	3	U4	U2	1	VREF
53	3	U1	V3	4	-
54	3	V4	V2	√	VREF
55	3	W3	W4	1	-
56	3	Y1	Y3	1	-
57	3	Y4	Y2	4	-
58	3	AA3	AB1	√	D5
59	3	AB3	AB4	√	VREF
60	3	AD1	AC3	1	VREF
61	3	AC4	AD2	4	-
62	3	AD3	AD4	√	VREF
63	3	AF2	AE3	1	-
64	3	AE4	AG1	5	-
65	3	AG2	AF3	1	VREF
66	3	AF4	AH1	4	-
67	3	AH2	AG3	3	-
68	3	AG4	AJ2	√	INIT
69	4	AJ4	AK3	√	-
70	4	AH5	AK4	1	-
71	4	AJ5	AH6	√	-
72	4	AL4	AK5	√	VREF
73	4	AJ6	AH7	2	-
74	4	AL5	AK6	√	-
75	4	AJ7	AL6	√	VREF
76	4	AH9	AJ8	1	-
77	4	AK8	AJ9	1	VREF
78	4	AL8	AK9	√	VREF
79	4	AK10	AL10	√	-

Table 13: BG432 Differential Pin Pair Summary
XCV300E, XCV400E, XC600E

Pair	Bank	P Pin	N Pin	AO	Other Functions
80	4	AH12	AK11	√	-
81	4	AJ12	AK12	√	-
82	4	AH13	AJ13	√	-
83	4	AL13	AK14	√	VREF
84	4	AH14	AJ14	1	-
85	4	AK15	AJ15	1	VREF
86	5	AH15	AL17	NA	IO_LVDS_DLL
87	5	AK17	AJ17	1	VREF
88	5	AH17	AK18	1	-
89	5	AL19	AJ18	√	VREF
90	5	AH18	AL20	√	-
91	5	AK20	AH19	√	-
92	5	AJ20	AK21	√	-
93	5	AJ21	AL22	√	-
94	5	AJ22	AK23	√	VREF
95	5	AH22	AL24	1	VREF
96	5	AK24	AH23	1	-
97	5	AK25	AJ25	√	VREF
98	5	AL26	AK26	√	-
99	5	AH25	AL27	2	-
100	5	AJ26	AK27	√	VREF
101	5	AH26	AL28	√	-
102	5	AJ27	AK28	1	-
103	6	AH30	AJ30	√	-
104	6	AH31	AG28	3	-
105	6	AG30	AG29	4	-
106	6	AG31	AF28	1	VREF
107	6	AF30	AF29	5	-
108	6	AF31	AE28	1	-
109	6	AD28	AE30	√	VREF
110	6	AD31	AD30	4	-
111	6	AC29	AC28	1	VREF

Table 15: BG560 Differential Pin Pair Summary
XCV400E, XCV600E, XCV1000E, XCV1600E, XCV2000E

Pair	Bank	P Pin	N Pin	AO	Other Functions
171	7	J33	M29	√	-
172	7	K31	L30	√	VREF
173	7	H33	L29	4	-
174	7	H32	J31	18	VREF
175	7	H31	K29	14	-
176	7	G32	J30	20	VREF
177	7	G31	J29	√	VREF
178	7	E32	E33	15	-
179	7	F31	H29	14	-
180	7	E31	D32	15	VREF
181	7	C33	G29	14	-
182	7	D31	F30	14	VREF

Notes:

1. AO in the XCV1600E.
2. AO in the XCV2000E.
3. AO in the XCV1600E, 2000E.
4. AO in the XCV1000E, 1600E.
5. AO in the XCV1000E, 2000E.
6. AO in the XCV1000E.
7. AO in the XCV1000E, 1600E, 2000E.
8. AO in the XCV600E, 1600E.
9. AO in the XCV400E, 600E, 1600E.
10. AO in the XCV400E, 600E, 1000E, 2000E.
11. AO in the XCV400E, 600E, 1000E.
12. AO in the XCV400E, 1000E, 2000E.
13. AO in the XCV400E, 600E, 1000E, 1600E.
14. AO in the XCV400E, 1000E, 1600E.
15. AO in the XCV600E, 1000E, 2000E.
16. AO in the XCV600E, 2000E.
17. AO in the XCV400E, 600E, 1600E, 2000E.
18. AO in the XCV600E, 1000E, 1600E, 2000E.
19. AO in the XCV400E, 600E, 2000E.
20. AO in the XCV400E, 1000E.

FG256 Fine-Pitch Ball Grid Array Packages

XCV50E, XCV100E, XCV200E, and XCV300E devices in FG256 fine-pitch Ball Grid Array packages have footprint compatibility. Pins labeled IO_VREF can be used as either in all parts unless device-dependent as indicated in the footnotes. If the pin is not used as V_{REF}, it can be used as general I/O. Immediately following Table 16, see Table 17 for Differential Pair information.

Table 16: FG256 Package — XCV50E, XCV100E, XCV200E, XCV300E

Bank	Pin Description	Pin #
0	GCK3	B8
0	IO	B3
0	IO	E7
0	IO	D8
0	IO_L0N_Y	C5
0	IO_VREF_L0P_Y	A3 ²
0	IO_L1N_YY	D5
0	IO_L1P_YY	E6
0	IO_VREF_L2N_YY	B4
0	IO_L2P_YY	A4
0	IO_L3N_Y	D6
0	IO_L3P_Y	B5
0	IO_VREF_L4N_YY	C6 ¹
0	IO_L4P_YY	A5
0	IO_L5N_YY	B6
0	IO_L5P_YY	C7
0	IO_L6N_Y	D7
0	IO_L6P_Y	C8
0	IO_VREF_L7N_Y	B7
0	IO_L7P_Y	A6
0	IO_LVDS_DLL_L8N	A7
1	GCK2	C9
1	IO	B10
1	IO_LVDS_DLL_L8P	A8
1	IO_L9N_Y	D9
1	IO_L9P_Y	A9
1	IO_L10N_Y	E10
1	IO_VREF_L10P_Y	B9

Table 18: FG456 — XCV200E and XCV300E

Bank	Pin Description	Pin #
NA	GND	M14
NA	GND	M13
NA	GND	M12
NA	GND	M11
NA	GND	M10
NA	GND	M9
NA	GND	L14
NA	GND	L13
NA	GND	L12
NA	GND	L11
NA	GND	L10
NA	GND	L9
NA	GND	K14
NA	GND	K13
NA	GND	K12
NA	GND	K11
NA	GND	K10
NA	GND	K9
NA	GND	J14
NA	GND	J13
NA	GND	J12
NA	GND	J11
NA	GND	J10
NA	GND	J9
NA	GND	C20
NA	GND	C3
NA	GND	B21
NA	GND	B2
NA	GND	A22
NA	GND	A1

Note 1: NC in the XCV200E device.

FG456 Differential Pin Pairs

Virtex-E devices have differential pin pairs that can also provide other functions when not used as a differential pair. A √ in the AO column indicates that the pin pair can be used as an asynchronous output for all devices provided in this package. Pairs with a note number in the AO column are device dependent. They can have asynchronous outputs if the pin pair are in the same CLB row and column in the device. Numbers in this column refer to footnotes that indicate which devices have pin pairs that can be asynchronous outputs. The Other Functions column indicates alternative function(s) not available when the pair is used as a differential pair or differential clock.

Table 19: FG456 Differential Pin Pair Summary
XCV200E, XCV300E

Pair	Bank	P Pin	N Pin	AO	Other Functions
Global Differential Clock					
0	4	W12	U12	NA	IO_DLL_L75P
1	5	Y11	AA11	NA	IO_DLL_L75N
2	1	A11	D11	NA	IO_DLL_L13P
3	0	C11	B11	NA	IO_DLL_L13N
IO LVDS					
Total Pairs: 119, Asynchronous Output Pairs: 69					
0	0	B3	D5	NA	-
1	0	E6	B4	√	VREF
2	0	E7	A4	NA	-
3	0	D6	C6	√	VREF
4	0	B6	A5	1	-
5	0	C7	D7	1	-
6	0	B7	E8	√	VREF
7	0	E9	A7	√	-
8	0	B8	C8	1	-
9	0	A8	D9	1	-
10	0	E10	C9	NA	-
11	0	C10	A9	√	VREF
12	0	B10	F11	2	-
13	1	D11	B11	NA	IO_LVDS_DLL
14	1	D12	C12	2	-
15	1	A13	B12	2	-
16	1	B13	E12	√	VREF
17	1	D13	C13	√	-

Table 23: FG680 Differential Pin Pair Summary
XCV600E, XCV1000E, XCV1600E, XCV2000E

Pair	Bank	P Pin	N Pin	AO	Other Functions
52	1	B8	A8	√	VREF
53	1	A7	D9	√	-
54	1	B7	C8	3	-
55	1	A6	D8	3	-
56	1	B6	C7	√	VREF
57	1	A5	D7	√	-
58	1	B5	C6	5	VREF
59	1	A4	D6	5	-
60	1	D5	B4	√	CS
61	2	E3	C2	√	DIN, D0
62	2	D3	F3	6	-
63	2	D2	G4	4	VREF
64	2	G3	E2	4	-
65	2	H4	E1	6	VREF
66	2	H3	F2	√	-
67	2	J4	F1	4	-
68	2	J3	G2	6	-
69	2	G1	K4	√	VREF
70	2	H2	K3	√	-
71	2	H1	L4	7	VREF
72	2	J2	L3	4	-
73	2	J1	M3	√	VREF
74	2	K2	N4	√	-
75	2	K1	N3	4	-
76	2	L2	P4	√	D1
77	2	P3	L1	√	D2
78	2	R4	M2	6	-
79	2	R3	M1	4	-
80	2	T4	N2	4	-
81	2	N1	T3	6	VREF
82	2	P2	U5	√	-
83	2	P1	U4	4	-
84	2	R2	U3	6	-
85	2	V5	R1	√	D3

Table 23: FG680 Differential Pin Pair Summary
XCV600E, XCV1000E, XCV1600E, XCV2000E

Pair	Bank	P Pin	N Pin	AO	Other Functions
86	2	V4	T2	√	-
87	2	V3	T1	7	-
88	2	W4	U2	4	-
89	2	W3	U1	√	VREF
90	2	AA3	V2	√	-
91	2	AA4	V1	4	VREF
92	2	AB2	W2	√	-
93	3	AB4	W1	4	VREF
94	3	AB5	Y2	√	-
95	3	AC2	Y1	√	VREF
96	3	AC3	AA1	4	-
97	3	AC4	AA2	7	-
98	3	AC5	AB1	√	-
99	3	AD3	AC1	√	VREF
100	3	AD1	AD4	6	-
101	3	AD2	AE3	4	-
102	3	AE1	AE4	√	-
103	3	AE2	AF3	6	VREF
104	3	AF4	AF1	4	-
105	3	AG3	AF2	4	-
106	3	AG4	AG1	6	-
107	3	AH3	AG2	√	D5
108	3	AH1	AJ2	√	VREF
109	3	AH2	AJ3	4	-
110	3	AJ1	AJ4	√	-
111	3	AK1	AK3	√	VREF
112	3	AK2	AK4	4	-
113	3	AL1	AL2	7	VREF
114	3	AM1	AL3	√	-
115	3	AM2	AL4	√	VREF
116	3	AM3	AN1	6	-
117	3	AM4	AP1	4	-
118	3	AN2	AP2	√	-
119	3	AN3	AR1	6	VREF

Table 23: FG680 Differential Pin Pair Summary
XCV600E, XCV1000E, XCV1600E, XCV2000E

Pair	Bank	P Pin	N Pin	AO	Other Functions
120	3	AN4	AT1	4	-
121	3	AR2	AP4	4	VREF
122	3	AT2	AR3	6	-
123	3	AR4	AU2	√	INIT
124	4	AU4	AV5	√	-
125	4	AT6	AV4	5	-
126	4	AU6	AW4	5	VREF
127	4	AT7	AW5	√	-
128	4	AU7	AV6	√	VREF
129	4	AT8	AW6	3	-
130	4	AU8	AV7	3	-
131	4	AT9	AW7	√	-
132	4	AV8	AU9	√	VREF
133	4	AW8	AT10	5	-
134	4	AV9	AU10	5	VREF
135	4	AW9	AT11	√	-
136	4	AV10	AU11	√	VREF
137	4	AW10	AU12	2	-
138	4	AV11	AT13	2	-
139	4	AW11	AU13	√	VREF
140	4	AT14	AV12	√	-
141	4	AU14	AW12	5	-
142	4	AT15	AV13	5	-
143	4	AU15	AW13	√	-
144	4	AV14	AT16	√	VREF
145	4	AW14	AU16	3	-
146	4	AV15	AR17	3	-
147	4	AW15	AT17	√	-
148	4	AU17	AV16	√	VREF
149	4	AR18	AW16	5	-
150	4	AT18	AV17	5	-
151	4	AU18	AW17	√	-
152	4	AT19	AV18	√	VREF
153	4	AU19	AW18	2	-

Table 23: FG680 Differential Pin Pair Summary
XCV600E, XCV1000E, XCV1600E, XCV2000E

Pair	Bank	P Pin	N Pin	AO	Other Functions
154	4	AU21	AV19	2	VREF
155	5	AT21	AT22	NA	IO_LVDS_DLL
156	5	AV20	AR22	8	VREF
157	5	AV23	AW21	√	VREF
158	5	AU23	AV21	√	-
159	5	AT23	AW22	5	-
160	5	AR23	AV22	5	-
161	5	AV24	AW23	√	VREF
162	5	AW24	AU24	√	-
163	5	AW25	AT24	3	-
164	5	AV25	AU25	3	-
165	5	AW26	AT25	√	VREF
166	5	AV26	AW27	√	-
167	5	AU26	AV27	5	-
168	5	AT26	AW28	5	-
169	5	AU27	AV28	√	-
170	5	AW29	AT27	√	VREF
171	5	AW30	AU28	2	-
172	5	AV30	AV29	2	-
173	5	AW31	AU29	√	VREF
174	5	AV31	AT29	√	-
175	5	AW32	AU30	5	VREF
176	5	AW33	AT30	5	-
177	5	AV33	AU31	√	VREF
178	5	AT31	AW34	√	-
179	5	AV32	AV34	3	-
180	5	AU32	AW35	3	-
181	5	AT32	AV35	√	VREF
182	5	AU33	AW36	√	-
183	5	AT33	AV36	5	VREF
184	5	AU34	AU36	5	-
185	6	AT38	AR36	√	-
186	6	AP36	AR38	6	-
187	6	AP37	AT39	4	VREF

Table 26: FG900 — XCV600E, XCV1000E, XCV1600E

Bank	Pin Description	Pin #
0	IO_L6N_Y	A5
0	IO_L6P_Y	F8
0	IO_L7N_Y	D7
0	IO_L7P_Y	N11
0	IO_L8N_YY	G9
0	IO_L8P_YY	E8
0	IO_VREF_L9N_YY	A6
0	IO_L9P_YY	J11
0	IO_L10N_Y	C7
0	IO_L10P_Y	B7
0	IO_L11N_Y	C8
0	IO_L11P_Y	H10
0	IO_L12N_YY	G10
0	IO_L12P_YY	F10
0	IO_VREF_L13N_YY	A8
0	IO_L13P_YY	H11
0	IO_L14N	D9 ⁴
0	IO_L14P	C9 ³
0	IO_L15N_YY	B9
0	IO_L15P_YY	J12
0	IO_L16N	E10 ⁴
0	IO_VREF_L16P	A9
0	IO_L17N	G11
0	IO_L17P	B10
0	IO_L18N_YY	H12 ⁴
0	IO_L18P_YY	C10 ⁴
0	IO_L19N_Y	H13
0	IO_L19P_Y	F11
0	IO_L20N_Y	E11
0	IO_L20P_Y	D11
0	IO_L21N_Y	B11 ⁴
0	IO_L21P_Y	G12 ⁴
0	IO_L22N_YY	F12
0	IO_L22P_YY	C11
0	IO_VREF_L23N_YY	A10 ¹
0	IO_L23P_YY	D12
0	IO_L24N_Y	E12

Table 26: FG900 — XCV600E, XCV1000E, XCV1600E

Bank	Pin Description	Pin #
0	IO_L24P_Y	A11
0	IO_L25N_Y	G13
0	IO_L25P_Y	B12
0	IO_L26N_YY	A12
0	IO_L26P_YY	K13
0	IO_VREF_L27N_YY	F13
0	IO_L27P_YY	B13
0	IO_L28N_Y	G14
0	IO_L28P_Y	E13
0	IO_L29N_Y	D14
0	IO_L29P_Y	B14
0	IO_L30N_YY	A14
0	IO_L30P_YY	J14
0	IO_VREF_L31N_YY	K14
0	IO_L31P_YY	J15
0	IO_L32N	B15 ⁴
0	IO_L32P	H15 ³
0	IO_VREF_L33N_YY	F15 ^{2,3}
0	IO_L33P_YY	D15 ⁴
0	IO_LVDS_DLL_L34N	A15
1	GCK2	E15
1	IO	A25 ⁴
1	IO	B17 ⁴
1	IO	B18 ⁴
1	IO	C23 ⁴
1	IO	D16 ⁴
1	IO	D17 ⁵
1	IO	D23 ⁴
1	IO	E19 ⁴
1	IO	E24 ⁵
1	IO	F22 ⁴
1	IO	G17 ⁵
1	IO	G20 ⁴
1	IO	J16 ⁴
1	IO	J17 ⁴
1	IO	J19 ⁵

Table 26: FG900 — XCV600E, XCV1000E, XCV1600E

Bank	Pin Description	Pin #
1	IO	J20 ⁵
1	IO	L18 ⁴
1	IO_LVDS_DLL_L34P	E16
1	IO_L35N_YY	B16
1	IO_VREF_L35P_YY	F16 ²
1	IO_L36N_YY	A16
1	IO_L36P_YY	H16
1	IO_L37N_YY	C16
1	IO_VREF_L37P_YY	K15
1	IO_L38N_YY	K16
1	IO_L38P_YY	G16
1	IO_L39N_Y	A17
1	IO_L39P_Y	E17
1	IO_L40N_Y	F17
1	IO_L40P_Y	C17
1	IO_L41N_YY	E18
1	IO_VREF_L41P_YY	A18
1	IO_L42N_YY	D18
1	IO_L42P_YY	A19
1	IO_L43N_Y	B19
1	IO_L43P_Y	G18
1	IO_L44N_Y	D19
1	IO_L44P_Y	H18
1	IO_L45N_YY	F18
1	IO_VREF_L45P_YY	F19 ¹
1	IO_L46N_YY	B20
1	IO_L46P_YY	K17
1	IO_L47N_Y	D20 ⁴
1	IO_L47P_Y	A20 ⁴
1	IO_L48N_Y	G19
1	IO_L48P_Y	C20
1	IO_L49N_Y	K18
1	IO_L49P_Y	E20
1	IO_L50N_YY	B21 ⁴
1	IO_L50P_YY	D21 ⁴
1	IO_L51N_YY	F20
1	IO_L51P_YY	A21

Table 26: FG900 — XCV600E, XCV1000E, XCV1600E

Bank	Pin Description	Pin #
1	IO_L52N_YY	C21
1	IO_VREF_L52P_YY	A22
1	IO_L53N_YY	H19
1	IO_L53P_YY	B22
1	IO_L54N_YY	E21
1	IO_L54P_YY	D22
1	IO_L55N_YY	F21
1	IO_VREF_L55P_YY	C22
1	IO_L56N_YY	H20
1	IO_L56P_YY	E22
1	IO_L57N_Y	G21
1	IO_L57P_Y	A23
1	IO_L58N_Y	A24
1	IO_L58P_Y	K19
1	IO_L59N_YY	C24
1	IO_VREF_L59P_YY	B24
1	IO_L60N_YY	H21
1	IO_L60P_YY	G22
1	IO_L61N_Y	E23
1	IO_L61P_Y	C25
1	IO_L62N_Y	D24
1	IO_L62P_Y	A26
1	IO_L63N_YY	B26
1	IO_VREF_L63P_YY	K20
1	IO_L64N_YY	D25
1	IO_L64P_YY	J21
1	IO_L65N_Y	C26 ⁴
1	IO_L65P_Y	F23 ⁴
1	IO_L66N_Y	B27
1	IO_VREF_L66P_Y	G23 ¹
1	IO_L67N_Y	A27
1	IO_L67P_Y	F24
1	IO_L68N_YY	B28 ³
1	IO_L68P_YY	A28 ⁴
1	IO_WRITE_L69N_YY	K21
1	IO_CS_L69P_YY	C27

Table 26: FG900 — XCV600E, XCV1000E, XCV1600E

Bank	Pin Description	Pin #
2	IO_L99P_YY	N26
2	IO_L99N_YY	P28
2	IO_L100P	P29
2	IO_L100N	N24
2	IO_L101P_YY	P22
2	IO_L101N_YY	R26
2	IO_VREF_L102P_YY	P25
2	IO_L102N_YY	R29
2	IO_L103P_YY	R21 ⁴
2	IO_L103N_YY	R28 ³
2	IO_VREF_L104P_YY	R25 ²
2	IO_L104N_YY	T30
2	IO_L105P_YY	P24 ⁴
2	IO_L105N_YY	R27 ³
2	IO_L106P	R24
3	IO	T22 ⁴
3	IO	T24 ⁴
3	IO	T26 ⁴
3	IO	T29 ⁴
3	IO	U26 ⁵
3	IO	V23 ⁴
3	IO	V25 ⁴
3	IO	V30 ⁵
3	IO	Y21 ⁴
3	IO	AA26 ⁴
3	IO	AA23 ⁴
3	IO	AB27 ⁴
3	IO	AB29 ⁴
3	IO	AC28 ⁵
3	IO	AD26 ⁴
3	IO	AD29 ⁵
3	IO	AE27 ⁵
3	IO_L106N	U29
3	IO_L107P_YY	R22
3	IO_VREF_L107N_YY	T27 ²
3	IO_L108P_YY	R23

Table 26: FG900 — XCV600E, XCV1000E, XCV1600E

Bank	Pin Description	Pin #
3	IO_L108N_YY	T28
3	IO_L109P_YY	T21
3	IO_VREF_L109N_YY	T25
3	IO_L110P_YY	U28
3	IO_L110N_YY	U30
3	IO_L111P	T23
3	IO_L111N	U27
3	IO_L112P_YY	U25
3	IO_L112N_YY	V27
3	IO_D4_L113P_YY	U24
3	IO_VREF_L113N_YY	V29
3	IO_L114P	W30
3	IO_L114N	U22
3	IO_L115P_YY	U21
3	IO_L115N_YY	W29
3	IO_L116P_YY	V26
3	IO_L116N_YY	W27
3	IO_L117P	W26
3	IO_VREF_L117N	Y29 ¹
3	IO_L118P_YY	W25
3	IO_L118N_YY	Y30
3	IO_L119P_Y	V24 ⁴
3	IO_L119N_Y	Y28 ⁴
3	IO_L120P_YY	AA30
3	IO_L120N_YY	W24
3	IO_L121P	AA29
3	IO_L121N	V20
3	IO_L122P	Y27 ⁴
3	IO_L122N	W23 ⁴
3	IO_L123P_YY	Y26
3	IO_D5_L123N_YY	AB30
3	IO_D6_L124P_YY	V21
3	IO_VREF_L124N_YY	AA28
3	IO_L125P_YY	Y25
3	IO_L125N_YY	AA27
3	IO_L126P_YY	W22
3	IO_L126N_YY	Y23

Table 26: FG900 — XCV600E, XCV1000E, XCV1600E

Bank	Pin Description	Pin #
5	IO_L182N	AF13
5	IO_L183P	AH14
5	IO_L183N	AJ14
5	IO_L184P_YY	AE14
5	IO_VREF_L184N_YY	AG13
5	IO_L185P_YY	AK13
5	IO_L185N_YY	AD13
5	IO_L186P	AE13
5	IO_L186N	AF12
5	IO_L187P	AC13
5	IO_L187N	AA13
5	IO_L188P_YY	AA12
5	IO_VREF_L188N_YY	AJ12 ¹
5	IO_L189P_YY	AB12
5	IO_L189N_YY	AE11
5	IO_L190P	AK12 ⁴
5	IO_L190N	Y13 ⁴
5	IO_L191P	AG11
5	IO_L191N	AF11
5	IO_L192P	AH11
5	IO_L192N	AJ11
5	IO_L193P_YY	AE12 ⁴
5	IO_L193N_YY	AG10 ⁴
5	IO_L194P_YY	AD12
5	IO_L194N_YY	AK11
5	IO_L195P_YY	AJ10
5	IO_VREF_L195N_YY	AC12
5	IO_L196P_YY	AK10
5	IO_L196N_YY	AD11
5	IO_L197P_YY	AJ9
5	IO_L197N_YY	AE9
5	IO_L198P_YY	AH10
5	IO_VREF_L198N_YY	AF9
5	IO_L199P_YY	AH9
5	IO_L199N_YY	AK9
5	IO_L200P	AF8
5	IO_L200N	AB11

Table 26: FG900 — XCV600E, XCV1000E, XCV1600E

Bank	Pin Description	Pin #
5	IO_L201P	AC11
5	IO_L201N	AG8
5	IO_L202P_YY	AK8
5	IO_VREF_L202N_YY	AF7
5	IO_L203P_YY	AG7
5	IO_L203N_YY	AK7
5	IO_L204P	AJ7
5	IO_L204N	AD10
5	IO_L205P	AH6
5	IO_L205N	AC10
5	IO_L206P_YY	AD9
5	IO_VREF_L206N_YY	AG6
5	IO_L207P_YY	AB10
5	IO_L207N_YY	AJ5
5	IO_L208P	AD8 ⁴
5	IO_L208N	AK5 ⁴
5	IO_L209P	AC9
5	IO_VREF_L209N	AJ4 ¹
5	IO_L210P	AG5
5	IO_L210N	AK4
5	IO_L211P_YY	AH5 ³
5	IO_L211N_YY	AG3 ⁴
6	IO	T2 ⁴
6	IO	T10 ⁴
6	IO	U1
6	IO	U4 ⁵
6	IO	U6 ⁴
6	IO	U7 ⁴
6	IO	V1 ⁴
6	IO	V5 ⁵
6	IO	V8
6	IO	Y10 ⁴
6	IO	AA4 ⁴
6	IO	AB5 ⁵
6	IO	AB7 ⁴
6	IO	AC3 ⁵

Table 26: FG900 — XCV600E, XCV1000E, XCV1600E

Bank	Pin Description	Pin #
7	IO	E3
7	IO	F1 ⁴
7	IO	G1 ⁵
7	IO	G4 ⁵
7	IO	H3 ⁵
7	IO	J1 ⁴
7	IO	J3 ⁴
7	IO	J4 ⁴
7	IO	J6 ⁴
7	IO	L10 ⁴
7	IO	N2 ⁴
7	IO	N8 ⁴
7	IO	N10 ⁴
7	IO	P3 ⁵
7	IO	P9 ⁴
7	IO	R1 ⁵
7	IO	T3 ⁴
7	IO_L247P	R10
7	IO_L248N_YY	R5 ³
7	IO_L248P_YY	R6 ⁴
7	IO_L249N_YY	R8
7	IO_VREF_L249P_YY	R4 ²
7	IO_L250N_YY	R7
7	IO_L250P_YY	R3
7	IO_L251N_YY	P10
7	IO_VREF_L251P_YY	P6
7	IO_L252N_YY	P5
7	IO_L252P_YY	P2
7	IO_L253N	P7
7	IO_L253P	P4
7	IO_L254N_YY	N4
7	IO_L254P_YY	R2
7	IO_L255N_YY	N7
7	IO_VREF_L255P_YY	P1
7	IO_L256N	M6

Table 26: FG900 — XCV600E, XCV1000E, XCV1600E

Bank	Pin Description	Pin #
7	IO_L256P	N6
7	IO_L257N_YY	N5
7	IO_L257P_YY	N1
7	IO_L258N_YY	M4
7	IO_L258P_YY	M5
7	IO_L259N	M2
7	IO_VREF_L259P	M1 ¹
7	IO_L260N_YY	L4
7	IO_L260P_YY	L2
7	IO_L261N_Y	M7 ⁴
7	IO_L261P_Y	L5 ⁴
7	IO_L262N_YY	L1
7	IO_L262P_YY	M8
7	IO_L263N	K2
7	IO_L263P	M9
7	IO_L264N	L3 ⁴
7	IO_L264P	M10 ⁴
7	IO_L265N_YY	K5
7	IO_L265P_YY	K1
7	IO_L266N_YY	L6
7	IO_VREF_L266P_YY	K3
7	IO_L267N_YY	L7
7	IO_L267P_YY	K4
7	IO_L268N_YY	L8
7	IO_L268P_YY	J5
7	IO_L269N_YY	K6
7	IO_VREF_L269P_YY	H4
7	IO_L270N_YY	H1
7	IO_L270P_YY	K7
7	IO_L271N	J7
7	IO_L271P	J2
7	IO_L272N_YY	H5
7	IO_L272P_YY	G2
7	IO_L273N_YY	L9
7	IO_VREF_L273P_YY	G5
7	IO_L274N	F3
7	IO_L274P	K8

Table 28: FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E

Bank	Pin Description	Pin #
NA	VCCINT	N22
NA	VCCINT	P13
NA	VCCINT	P22
NA	VCCINT	R13
NA	VCCINT	R22
NA	VCCINT	T13
NA	VCCINT	T22
NA	VCCINT	U10
NA	VCCINT	U25
NA	VCCINT	V10
NA	VCCINT	V25
NA	VCCINT	W13
NA	VCCINT	W22
NA	VCCINT	Y13
NA	VCCINT	Y22
NA	VCCINT	AA13
NA	VCCINT	AA22
NA	VCCINT	AB13
NA	VCCINT	AB14
NA	VCCINT	AB15
NA	VCCINT	AB16
NA	VCCINT	AB19
NA	VCCINT	AB20
NA	VCCINT	AB21
NA	VCCINT	AB22
NA	VCCINT	AC12
NA	VCCINT	AC23
NA	VCCINT	AD24
NA	VCCINT	AD11
NA	VCCINT	AE10
NA	VCCINT	AE17
NA	VCCINT	AE18
NA	VCCINT	AE25

Table 28: FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E

Bank	Pin Description	Pin #
NA	VCCO_0	M17
NA	VCCO_0	L17
NA	VCCO_0	L16
NA	VCCO_0	E10
NA	VCCO_0	C14
NA	VCCO_0	A6
NA	VCCO_0	M13
NA	VCCO_0	M14
NA	VCCO_0	M15
NA	VCCO_0	M16
NA	VCCO_0	L12
NA	VCCO_0	L13
NA	VCCO_0	L14
NA	VCCO_0	L15
NA	VCCO_1	M18
NA	VCCO_1	L18
NA	VCCO_1	L23
NA	VCCO_1	E25
NA	VCCO_1	C21
NA	VCCO_1	A29
NA	VCCO_1	M19
NA	VCCO_1	M20
NA	VCCO_1	M21
NA	VCCO_1	M22
NA	VCCO_1	L19
NA	VCCO_1	L20
NA	VCCO_1	L21
NA	VCCO_1	L22
NA	VCCO_2	U24
NA	VCCO_2	U23
NA	VCCO_2	N24
NA	VCCO_2	M24
NA	VCCO_2	K30
NA	VCCO_2	F34